

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



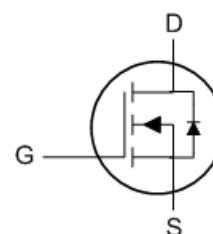
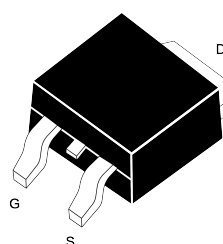
BVDSS	RDSON	ID
650V	0.35 Ω	11A

## Applications

The JH650SJ32 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The JH650SJ32 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## TO-252 Pin Configuration



## Absolute Maximum Ratings

Parameter	Symbol	WMK/WMM/WMO/WMP/WMN	WML	Unit
Drain-source voltage	$V_{DSS}$	650		V
Continuous drain current <sup>1)</sup> ( $T_C = 25^\circ\text{C}$ ) ( $T_C = 100^\circ\text{C}$ )	$I_D$	11		A
		6.5		A
Pulsed drain current <sup>2)</sup>	$I_{DM}$	32		A
Gate-source voltage	$V_{GS}$	±30		V
Avalanche energy, single pulse <sup>3)</sup>	$E_{AS}$	145		mJ
Avalanche energy, repetitive <sup>2)</sup>	$E_{AR}$	0.21		mJ
Avalanche current, repetitive <sup>2)</sup>	$I_{AR}$	2		A
Power dissipation ( $T_C = 25^\circ\text{C}$ ) - D rate above $25^\circ\text{C}$	$P_D$	85	31	W
		0.68	0.25	W/ $^\circ\text{C}$
Operating and storage temperature range	$T_j, T_{stg}$	-55 to +150		$^\circ\text{C}$
Continuous diode forward current	$I_S$	11		A
Diode pulse current	$I_{S,pulse}$	35		A
MOSFET dv/dt ruggedness	dv/dt	50		V/ns
Peak diode recovery voltage slope	dv/dt	15		V/ns

## Thermal Characteristics

Parameter	Symbol	WMK/WMM/WMO/WMP/WMN	WML	Unit
Thermal resistance, junction-to-case	$R_{\theta JC}$	1.47	4	$^{\circ}\text{C/W}$
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	62	80	$^{\circ}\text{C/W}$

## Electrical Characteristics $T_c = 25^{\circ}\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0\text{ V}, I_D=0.25\text{ mA}$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=0.25\text{ mA}$	2	3	4	V
Drain cut-off current	$I_{DSS}$	$V_{DS}=700\text{ V}, V_{GS}=0\text{ V},$ $T_j = 25^{\circ}\text{C}$ $T_j = 125^{\circ}\text{C}$	-	-	1	$\mu\text{A}$
Gate leakage current, forward	$I_{GSSF}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Gate leakage current, reverse	$I_{GSSR}$	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=2\text{ A}$	--	0.35	0.39	$\Omega$
<b>Dynamic characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V},$ $f=1\text{ MHz}$	-	710	-	pF
Output capacitance	$C_{oss}$		-	25	-	
Reverse transfer capacitance	$C_{rss}$		-	2	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=300\text{ V}, I_D=5\text{ A}$ $R_G=25\Omega, V_{GS}=10\text{ V}$	-	20	-	ns
Rise time	$t_r$		-	16	-	
Turn-off delay time	$t_{d(off)}$		-	61	-	
Fall time	$t_f$		-	17	-	
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{gs}$	$V_{DD}=480\text{ V}, I_D=5\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	3.4	-	nC
Gate to drain charge	$Q_{gd}$		-	10.1	-	
Gate charge total	$Q_g$		-	20.3	-	
Gate plateau voltage	$V_{plateau}$		-	4.7	-	V
<b>Reverse diode characteristics</b>						
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=2\text{ A}$	-	-	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=50\text{ V}, I_F=5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	213	-	ns
Reverse recovery charge	$Q_{rr}$		-	2.1	-	$\mu\text{C}$
Peak reverse recovery current	$I_{rrm}$		-	20	-	A

### Notes:

- Limited by  $T_{j\text{max}}$ . Maximum duty cycle  $D=0.5$ .
- Repetitive rating: pulse width limited by maximum junction temperature.
- $I_{AS}=2\text{ A}, V_{DD}=50\text{ V}, R_G=25\Omega$ , starting  $T_j=25^{\circ}\text{C}$ .

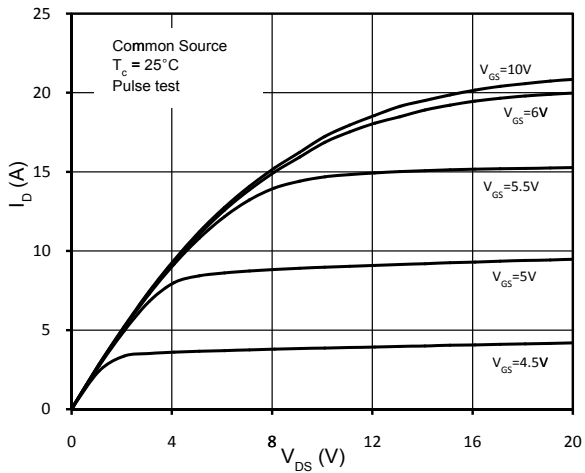


Figure 1. On-Region Characteristics

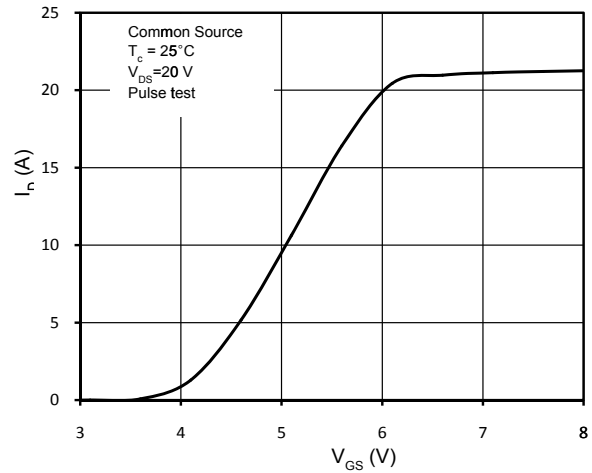


Figure 2. Transfer Characteristics

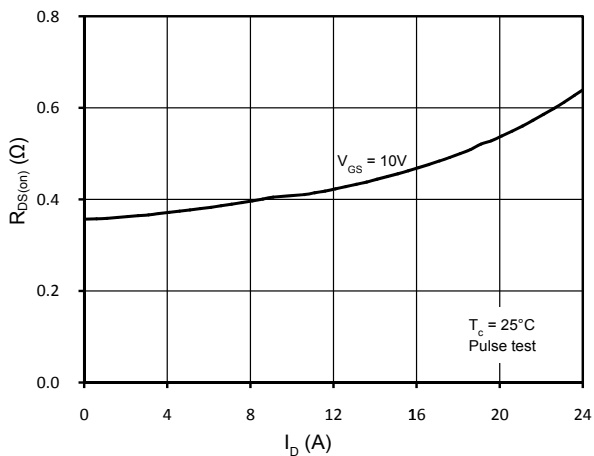


Figure 3. Static Drain-Source On Resistance

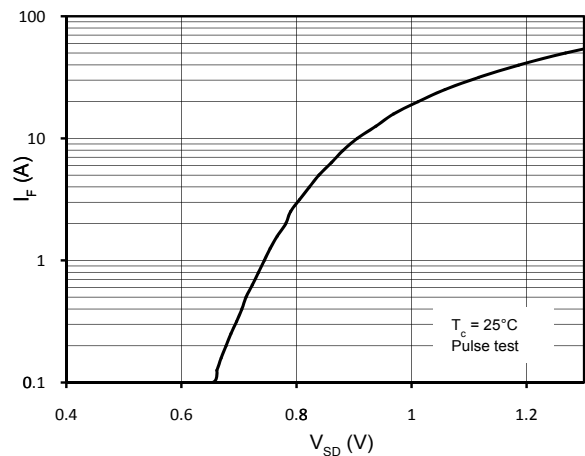


Figure 4. Body-Diode Forward Characteristics

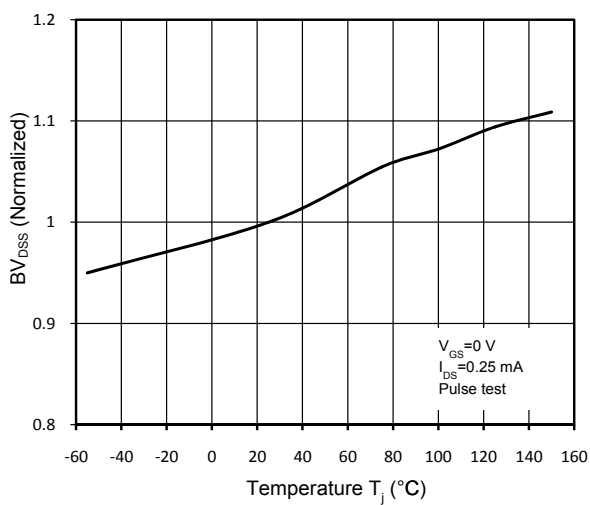


Figure 5. Normalized  $BV_{DS}$  vs. Temperature

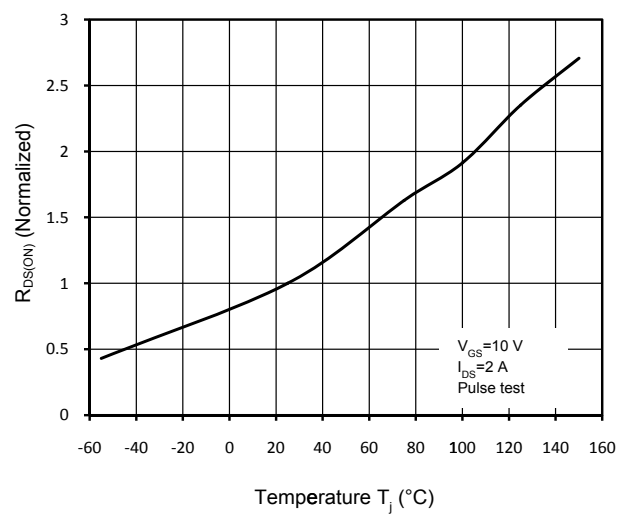


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

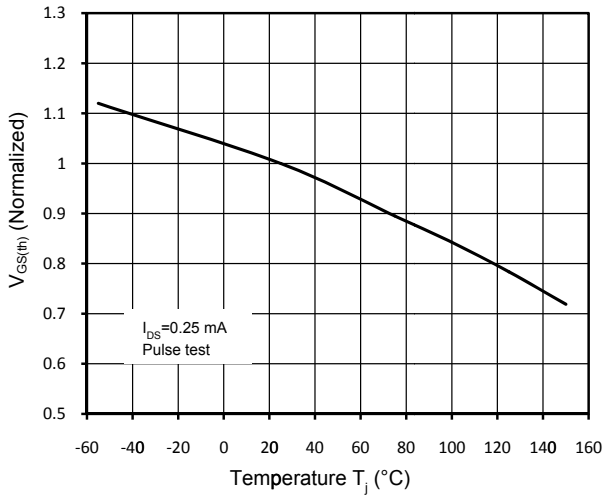


Figure 7. Threshold Voltage vs. Temperature

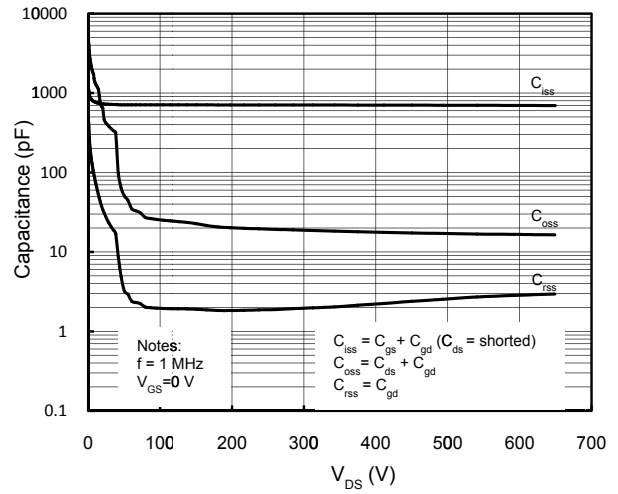


Figure 8. Capacitance Characteristics

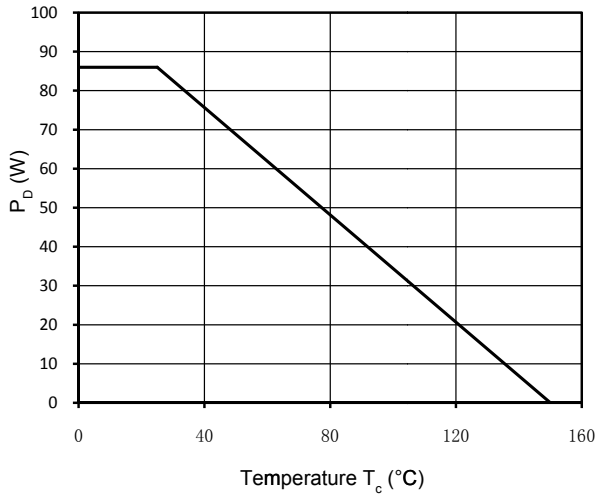


Figure 9. Power Dissipation

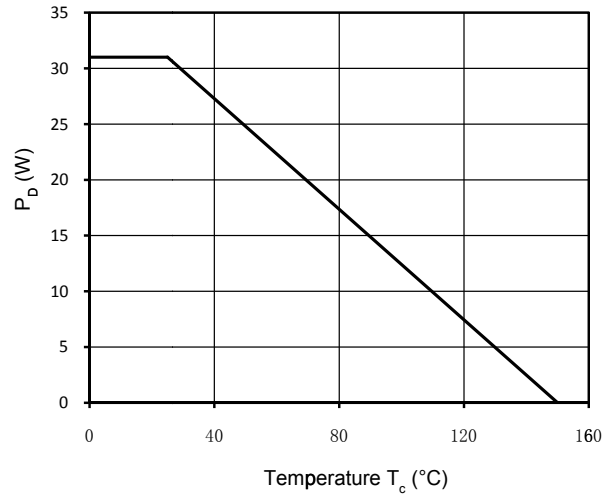


Figure 10. Power Dissipation (TO-220F)

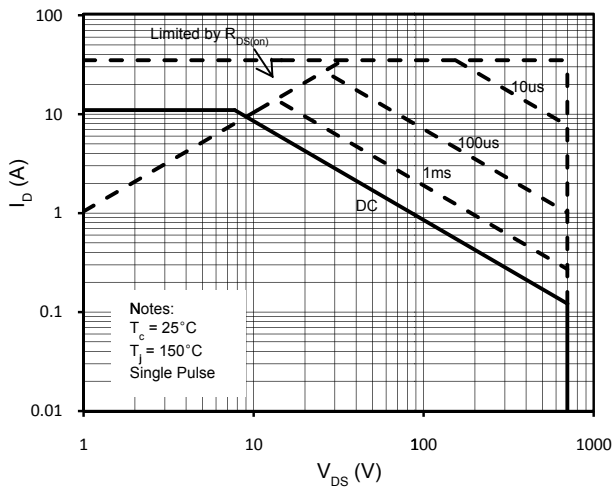


Figure 11. Maximum Safe Operating Area

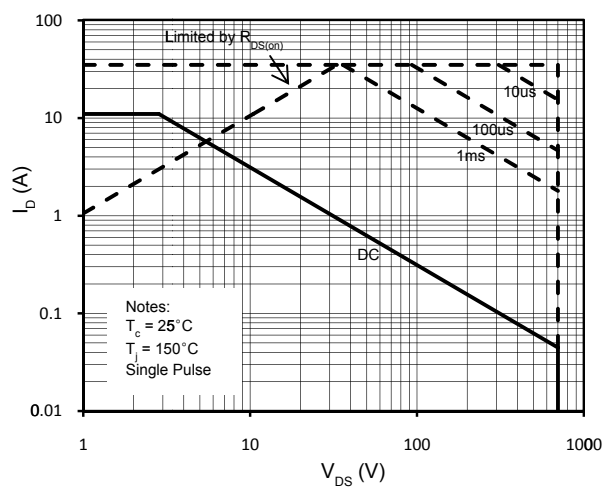


Figure 12. Maximum Safe Operating Area (TO-220F)

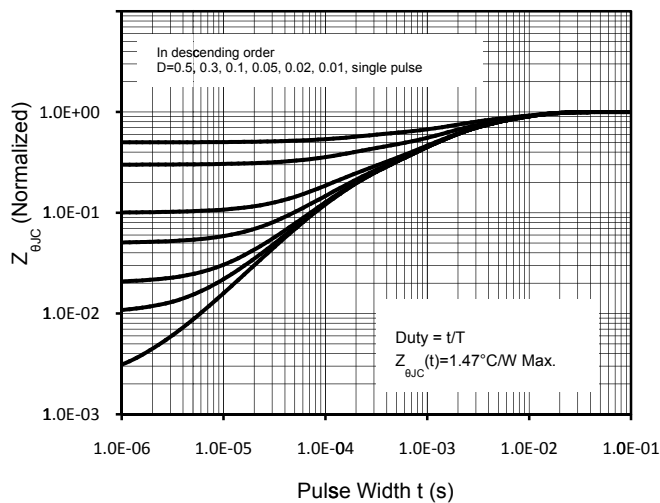
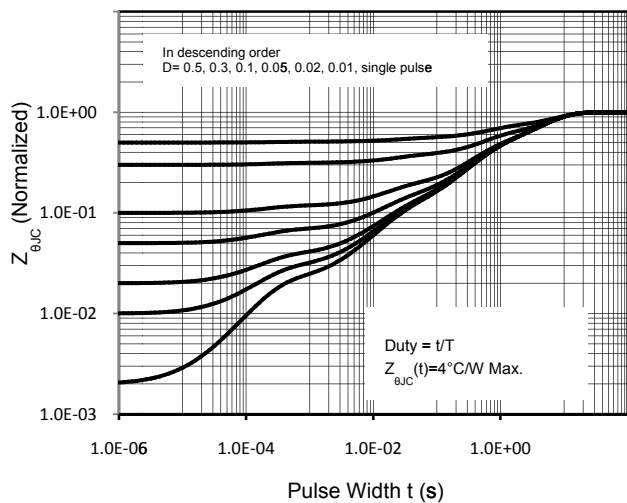


Figure 13. Transient Thermal Response Curve (TO-220F) Figure 14. Transient Thermal Response Curve

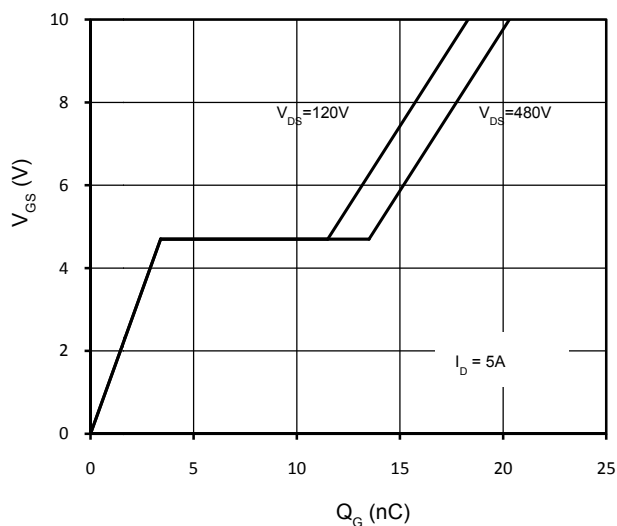
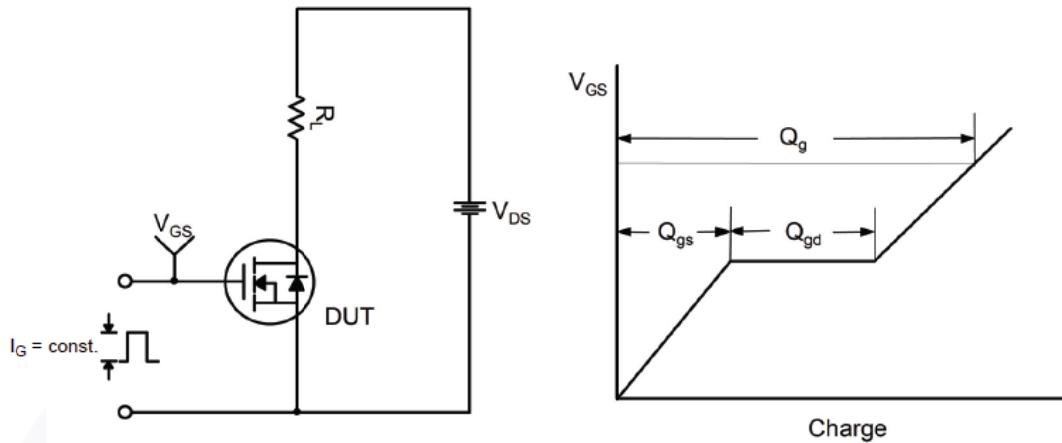
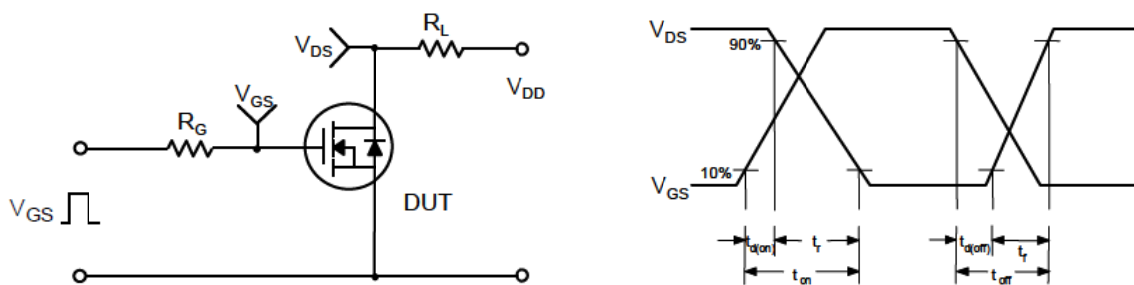


Figure 15. Gate Charge Characteristics

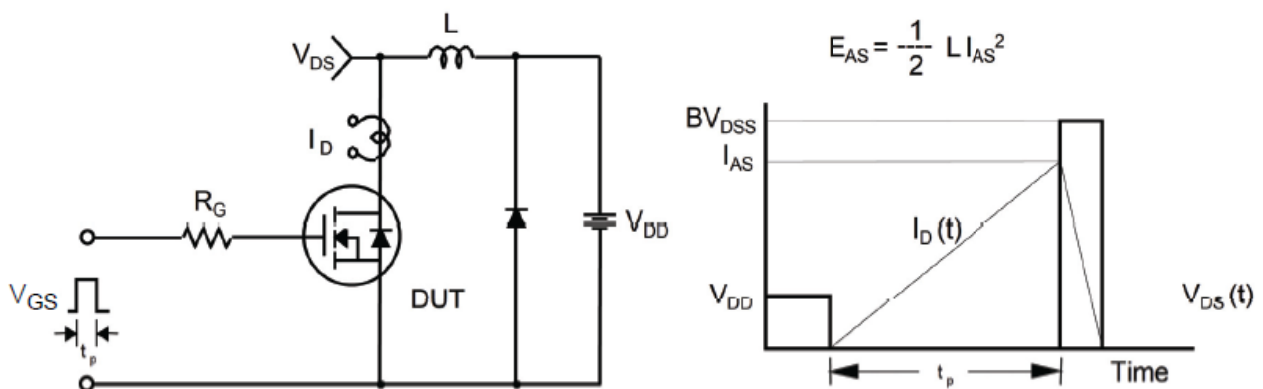
### Gate Charge Test Circuit & Waveform



### Switching Test Circuit & Waveforms

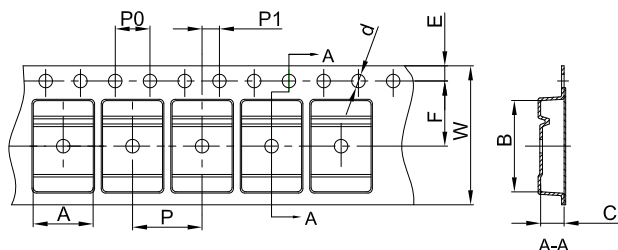


### Unclamped Inductive Switching Test Circuit & Waveforms



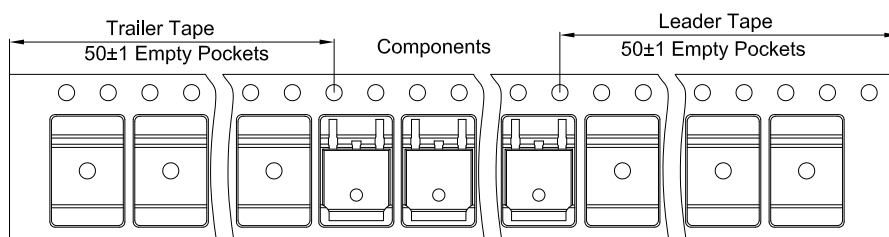
## TO-252-2L Tape and Reel

### TO-252 Embossed Carrier Tape

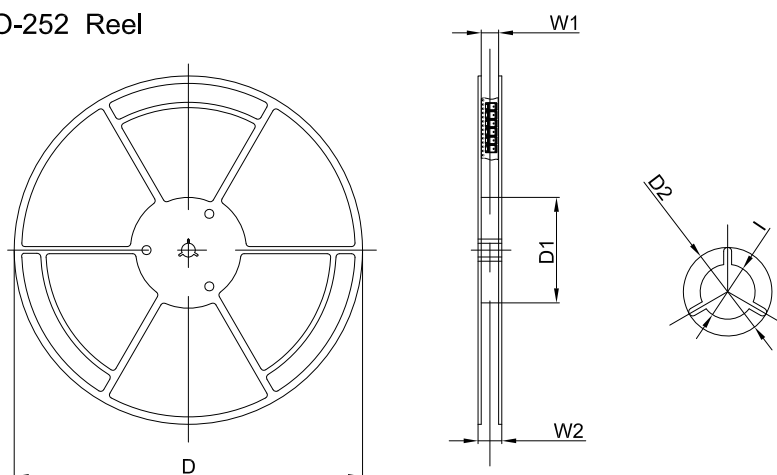


Dimensions are in millimeter										
Pkg type	A	B	C	d	E	F	P0	P	P1	W
TO-252	6.90	10.50	2.70	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00

### TO-252 Tape Leader and Trailer

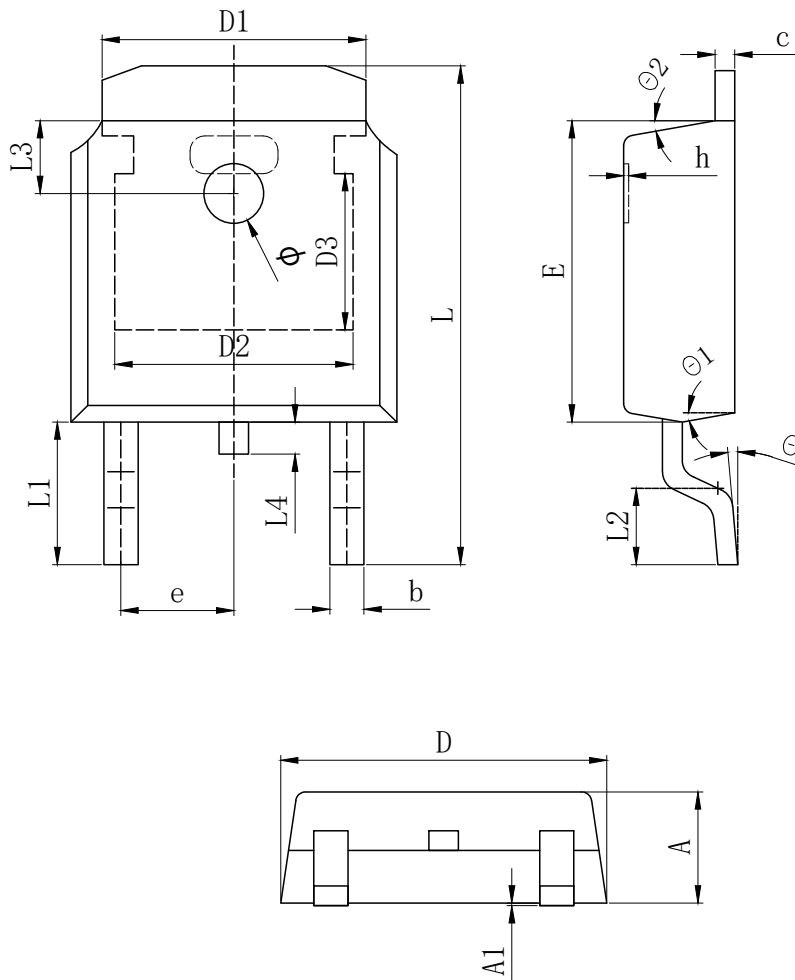


### TO-252 Reel



Dimensions are in millimeter						
Reel Option	D	D1	D2	W1	W2	l
13"Dia	330.00	100.00	Ø21.00	16.40	21.00	Ø13.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13inch	2,500 pcs	340×336×29	25,000 pcs	353×346×365	



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
$\phi$	1.100	1.200	1.300
$\theta$	0°		8°
$\theta_1$	9° TYP		
$\theta_2$	9° TYP		

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